

JSO21 Series Material Declaration

Total Weight: 7,0 mg
Size: 2.0 x 1.6 x 0.75 mm



RoHS (2011/65/EC) compliant



Part	Weight of parts (mg)	Content substance	CAS No	Content (mg)	Content (wt%)	
Leadframe	1.904	C194 Alloy	Copper	7440-50-8	1.857	26.65
			Iron	7439-89-6	0.045	0.65
			Zinc	7440-66-6	0.002	0.03
Plating	0.027	NiPdAu	Nickel	7440-02-0	0.026	0.37
			Palladium	7440-05-3	0.001	0.01
			Gold	7440-57-5	<0.001	Trace
Die 1	0.5	CEMOS Die	Si	7440-21-3	0.500	7.18
Die 2	0.04	MEMS Die	Si	7440-21-3	0.040	0.57
Die attach material 1	0.256	Non-Conductive epoxy	Epoxy Resin	Proprietary	0.180	2.58
			Glycol Ether	25068-38-6	0.038	0.54
			Fused Silica	60676-86-0	0.020	0.29
			Additive	Proprietary	0.018	0.26
Die attach material 2	0.022	Conductive epoxy	Silver	7440-22-4	0.017	0.24
			Acrylate	Proprietary	0.004	0.06
			Resin	Proprietary	0.001	0.01
			Additive	Proprietary	<.001	Trace
Wire	0.054	Gold	Au	7440-57-5	0.054	0.78
Encapsulation	4.166	Epoxy Resin	Fused silica	60676-86-0	3.77	54.1
			Epoxy resin	Proprietary	0.196	2.81
			Phenol resin	Proprietary	0.196	2.81
			Carbon black	1333-86-4	0.004	0.06